Product Change Notification: MFOL-09DZHN591

Date:

16-Nov-2026

Product Category:

8-Bit Microcontrollers, Capacitive Touch Sensors, Memory

Notification Subject:

CCB 8447.001 Initial Notice: Qualification of G630AY as an additional mold compound for selected 25LC010A, 25AA010A, PIC10F202, PIC10F204, 24VL014, 24LC014, 24AA014, PIC10F220, PIC10F222, MTCH101, 25LC020A, 25AA020A, 25AA02E48, 25AA02E64, 25AA02UID, 25LC040A, 25AA040A, PIC10F200, PIC10F206, 24VL025, 24LC025, 24AA025, 24C01C, 34VL02, 34LC02, 34AA02, 24AA025E48, 24AA025E64 and 24AA025UID device families available in 6L SOT-23 (1.6mm) package at MTAI assembly site.

Affected CPNs:

MFOL-09DZHN591_Affected_CPN_11162026.pdf
MFOL-09DZHN591_Affected_CPN_11162026.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of G630AY as an additional mold compound for selected 25LC010A, 25AA010A, PIC10F202, PIC10F204, 24VL014, 24LC014, 24AA014, PIC10F220, PIC10F222, MTCH101, 25LC020A, 25AA020A, 25AA02E48, 25AA02E64, 25AA02UID, 25LC040A, 25AA040A, PIC10F200, PIC10F206, 24VL025, 24LC025, 24AA025, 24C01C, 34VL02, 34LC02, 34AA02, 24AA025E48, 24AA025E64 and 24AA025UID device families available in 6L SOT-23 (1.6mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)		No
Wire Material	CuPdAu	CuPdAu		No
Die Attach Material	8006NS (PFAS-free)	8006NS (PFAS-free)		No
Molding Compound Material	G600V	G600V	G630AY	Yes
Lead-Frame Material	CDA194	CDA194		No
Lead-Frame Paddle Size	72 x 41 mils	72 x 41 mils		No
Lead-Frame DAP Surface Prep	Ag-RT	Ag	Ag-RT	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying G630AY as an additional mold compound at MTAI assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: December 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	November 2026				December 2026				
Work Week	45	46	47	48	49	50	51	52	53
Initial PCN Issue Date			**x**						
Qual Report Availability							x		
Final PCN Issue Date							x		

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: November 16, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-09DZHN591_Qual_Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.